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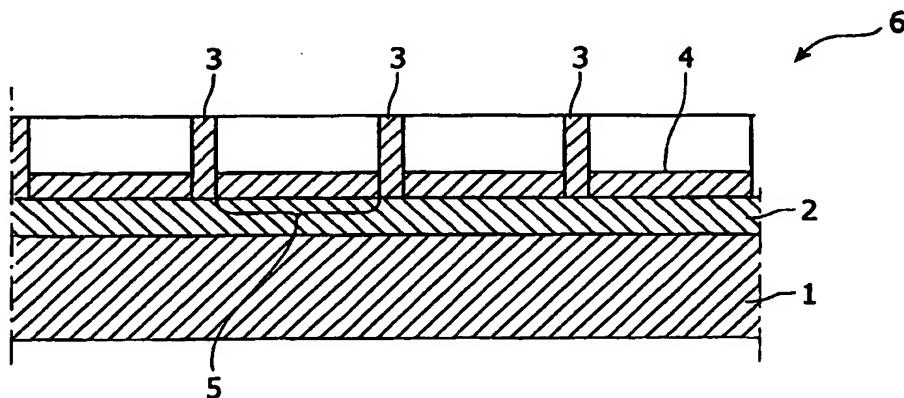
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(71) Applicant (for all designated States except US): KONINKLIJKE PHILIPS ELECTRONICS N.V. [NL/NL]; Groenewoudseweg 1, NL-5621 BA Eindhoven (NL).  
(72) Inventors; and  
(75) Inventors/Applicants (for US only): DUINEVELD, Paulus, C. [NL/NL]; c/o Prof. Holstlaan 6, NL-5656 AA Eindhoven (NL). SLIKKERVEER, Peter, J. [NL/NL]; c/o Prof. Holstlaan 6, NL-5656 AA Eindhoven (NL).  
(74) Agent: ELEVeld, Koop, J.; Prof. Holstlaan 6, NL-5656 AA Eindhoven (NL).  
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(54) Title: THIN FILM PATTERNING ARRANGEMENT



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(57) Abstract: A thin film patterning arrangement (6), comprising a substrate (1) and barriers (3) arranged to partition a surface of the substrate (1) into sub-areas (5) is disclosed. Said surface is of a polymeric material, and is coated with an at least partly inorganic coating (2). Thin film material (4) is preferably deposited on said thin film patterning arrangement (6).



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